ABSTRACT

SINGLE UNIT AUTOMATED ASSEMBLY OF FLEX ENHANCED BALL GRID ARRAY PACKAGES

A new package is provided for the mounting of IC devices. The IC die is bonded to metal traces contained in a flexible tape, the IC die with the flexible tape is attached to a stiffener (heat spreader), the various heat conducting interfaces are cured and solder balls are attached to another surface of the flexible tape. (Fig. 7)